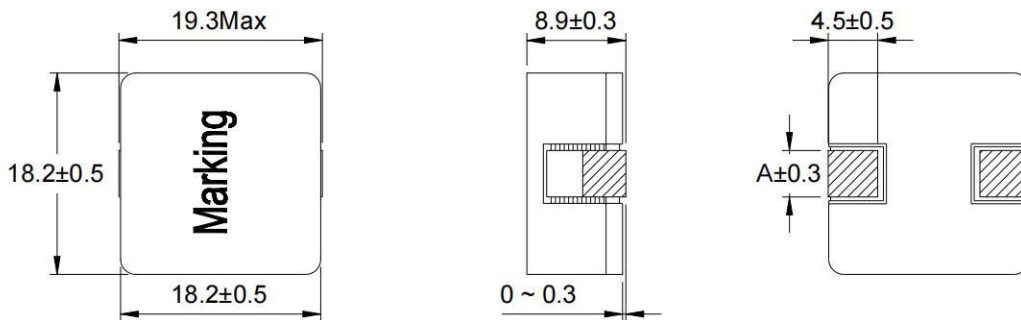


Outline: 产品概要

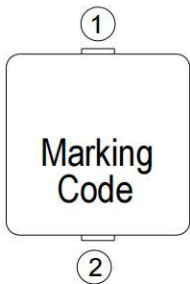
- Magnetic shielded structure: excellent resistance to electro magnetic interference(EMI)
磁屏蔽结构：抗电磁干扰(EMI)性能强
- Flat wire winding, achieve a low D.C. Resistance.
扁平线绕组，实现极低的直流电阻。
- Low loss, high efficiency, wide application frequency and application scope.
低损耗，高效率，应用频率宽，适用范围广。
- Lightweight design, save space, suitable for high density SMT.
轻薄型设计，节省空间，适合高密度贴装。
- Operating temperature : -55°C ~ +150°C (Including coil's temperature rise)
工作温度：-55°C ~ +150°C (包含线圈发热)

1 Appearance and Dimensions (mm) 外形尺寸 (mm)

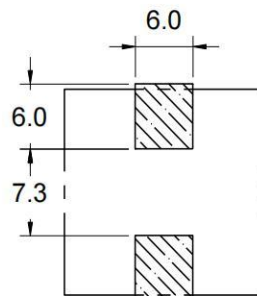


Part No.	R82 - 150	220	330 - 560
Dimension A	4.0	3.5	3.2

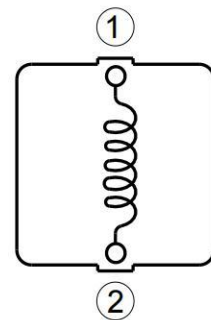
2 Marking 印字标识



3 Reference Land Pattern (mm) 参考基板尺寸 (mm)



4 Schematic 原理图



※ Date code will be changed by manufacture date.
生产日期代码将根据生产日期变动。



5 Electrical Characteristics

电气特性

Part No. 型号	Inductance (μH) 电感值 ※1 ±20%	D.C.R. (mΩ) 直流电阻		Saturation current (A) 饱和电流 ※2 Typical	Temperature rise current (A) 温升电流 ※3 Typical
		Typical	Max		
YZBX1809-R82M	0.82	0.54	0.62	88.0	41.5
YZBX1809-1R3M	1.30	0.85	1.00	67.0	36.0
YZBX1809-2R0M	2.00	1.20	1.38	58.0	32.5
YZBX1809-2R7M	2.70	1.58	1.82	50.0	31.5
YZBX1809-3R6M	3.60	2.20	2.60	43.0	25.0
YZBX1809-4R7M	4.70	2.85	3.40	39.0	22.5
YZBX1809-5R6M	5.60	3.18	3.70	35.0	21.0
YZBX1809-6R8M	6.80	4.10	4.70	31.0	18.5
YZBX1809-8R5M	8.50	4.82	5.55	28.0	18.0
YZBX1809-100M	10.0	6.00	6.90	26.0	16.0
YZBX1809-150M	15.0	8.20	9.43	22.0	14.0
YZBX1809-220M	22.0	12.1	14.1	17.5	11.0
YZBX1809-330M	33.0	20.0	23.0	14.0	8.50
YZBX1809-470M	47.0	33.7	38.8	11.5	6.80
YZBX1809-560M	56.0	35.8	41.2	10.8	6.50

- All data is tested based on 25°C ambient temperature.
所有数据基于环境温度 25°C 条件下测试。

※1 Inductance measure condition at 100kHz, 0.5V.
电感测试条件为 100kHz, 0.5V。

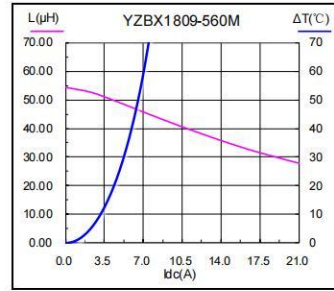
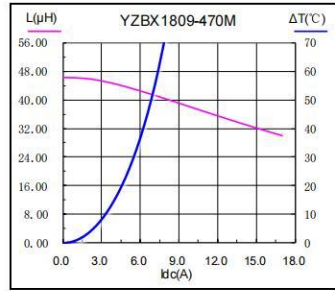
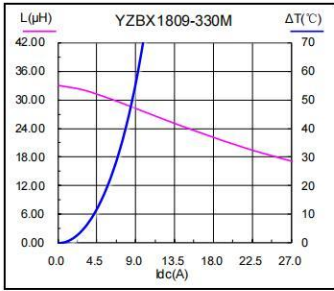
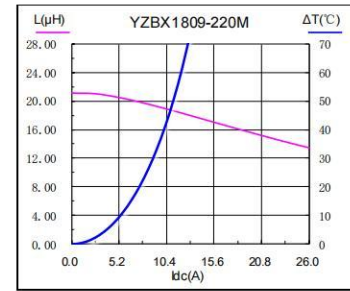
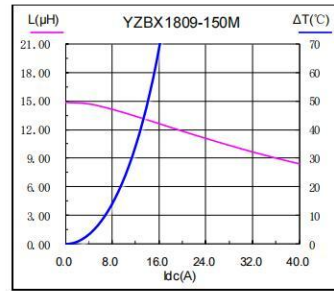
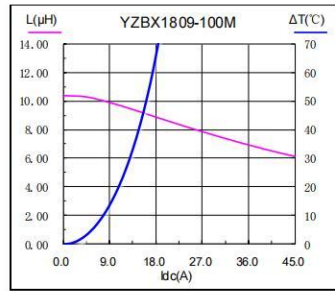
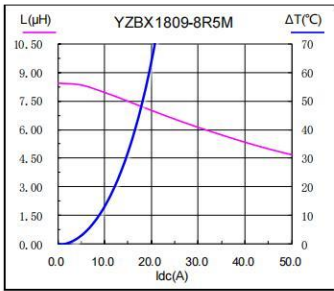
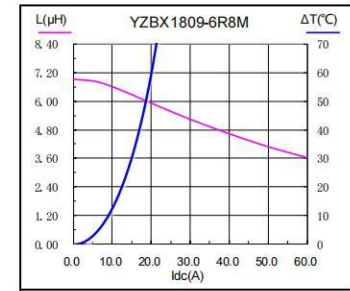
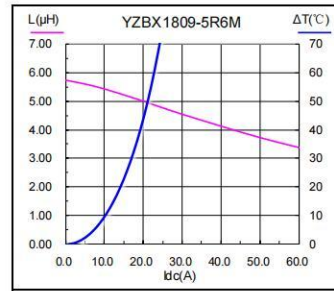
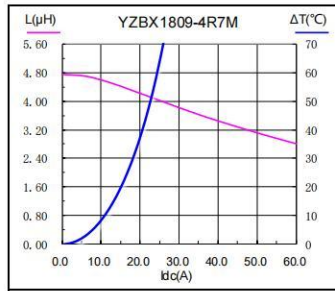
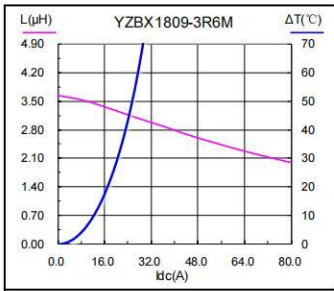
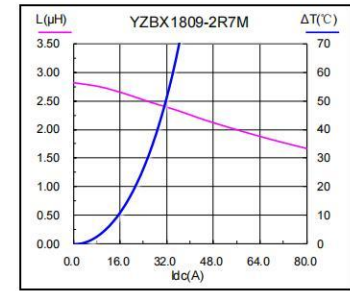
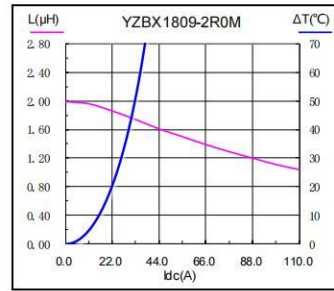
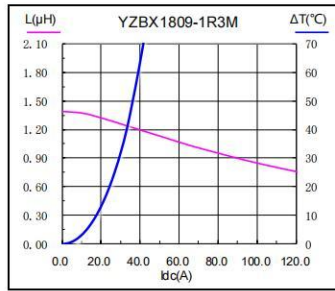
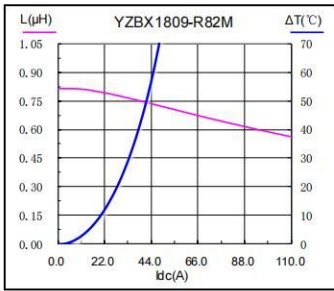
※2 Saturation current : the actual value of DC current when the inductance decrease 30% of its initial value.
饱和电流 : 电感值下降其初始值的 30% 时所加载的实际直流电流值。

※3 Temperature rise current : the actual value of DC current when the temperature rise is $\Delta T 50^{\circ}\text{C}$ ($T_a=25^{\circ}\text{C}$).
温升电流 : 使产品温度上升到 $\Delta T 50^{\circ}\text{C}$ 时所加载的实际直流电流值 ($T_a=25^{\circ}\text{C}$)。

※ Special remind : Circuit design, component placement, PCB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.
特别提醒 : 线路设计, 组件布局, 印刷电路板 (PCB) 尺寸及厚度, 散热系统等均会影响产品温度。请务必在最终应用时, 验证产品发热状况。



6 Saturation Current vs Temperature Rise Current Curve 饱和电流 vs 温升电流曲线

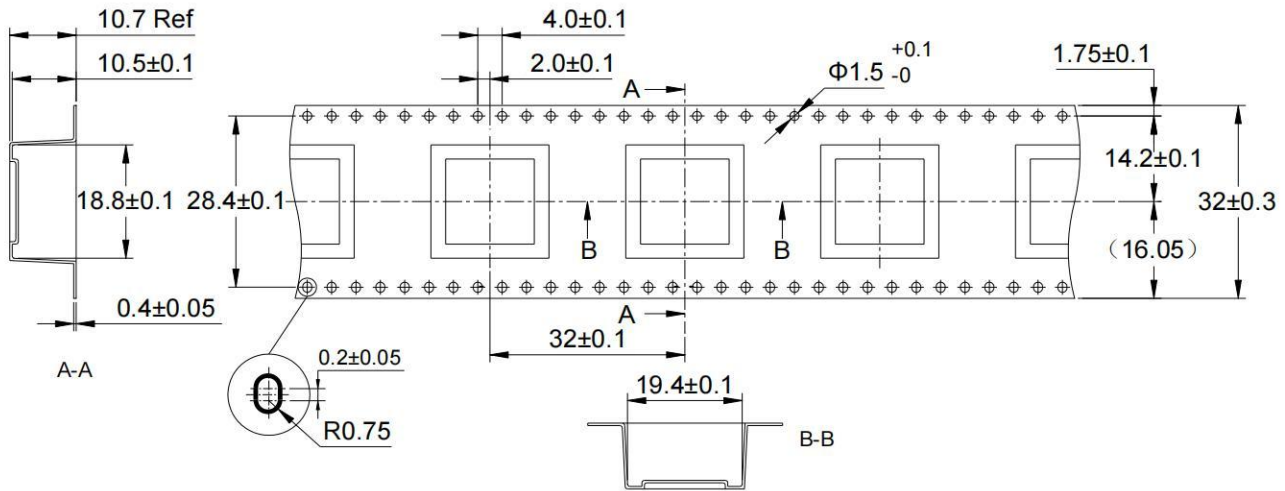


7 Packing Specification

包装规格

7.1 Carrier Tape Dimensions (mm)

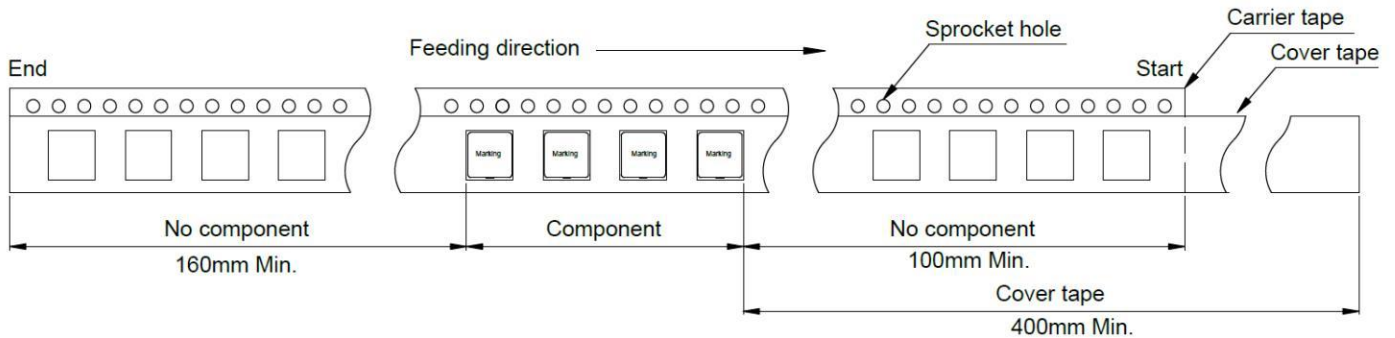
载带尺寸



※ Packing is referred to the international standard IEC 60286-3.
包装参照国际标准 IEC 60286-3。

7.2 Tape Direction

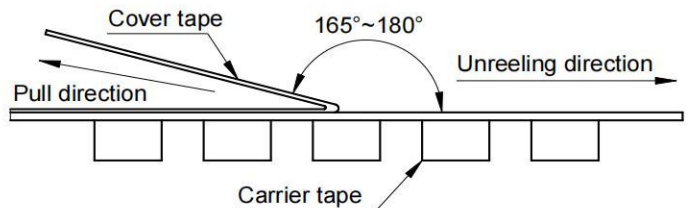
捆包方向



7.3 Cover Tape Peel Off Condition

盖带剥离条件

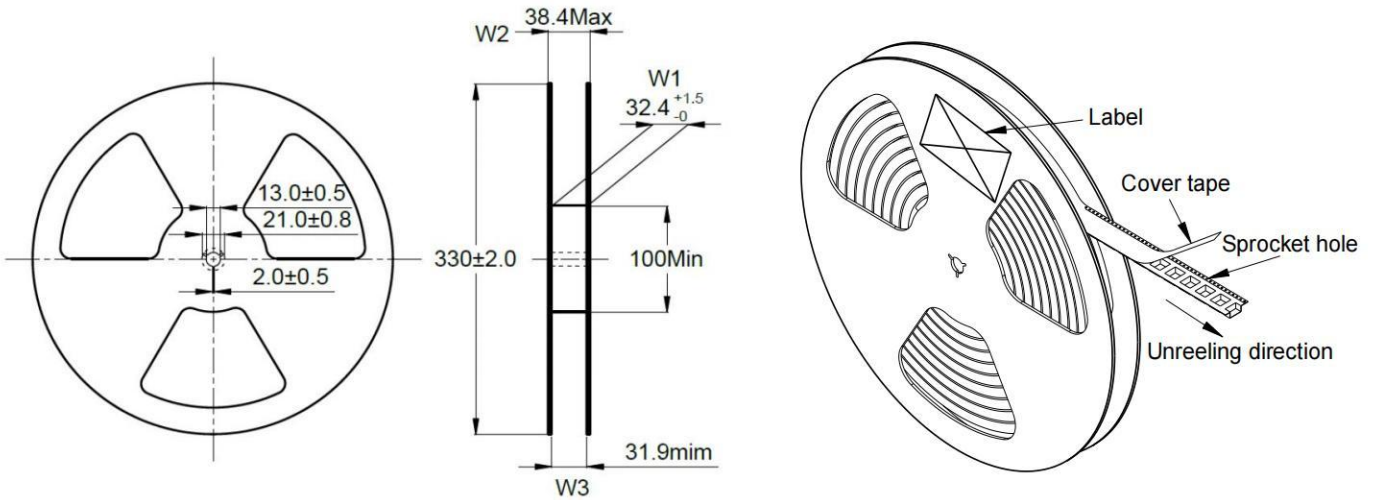
- Cover tape peel force shall be 0.1 to 1.3N.
盖带剥离力度为 0.1 ~ 1.3N。
- Reference peel speed 300±10mm/min.
参考剥离速度 300±10mm/分钟。





7.4 Reel Dimensions (mm)

卷盘尺寸



7.5 Carton Dimensions and Packing Quantity

包装箱尺寸和包装数量

■ Inner Carton : 340×340×95mm
内包装盒

■ Out Carton : 360×360×370mm
外包装箱

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 包装总数量
YZBX1809	150pcs	(150×2) = 300pcs	(300×3) = 900pcs

7.6 Label Making

标签标识

The following items will be marked on the tray of product label and shipping label.
以下项目将明确标识于产品吸塑盘标签以及运输标签上。

Production Label 产品标签
■ Packing No. 包装流水号
■ Quantity 数量
■ Shipment Date 出货日期
■ Part No. 产品型号
■ Customer Part No. 客户型号
■ Customer Po No. 客户订单号

Shipping Label 运输标签
■ Packing No. 包装流水号
■ Quantity 数量
■ Shipment Date 出货日期
■ Part No. 产品型号
■ Customer Part No. 客户型号
■ Customer Po No. 客户订单号

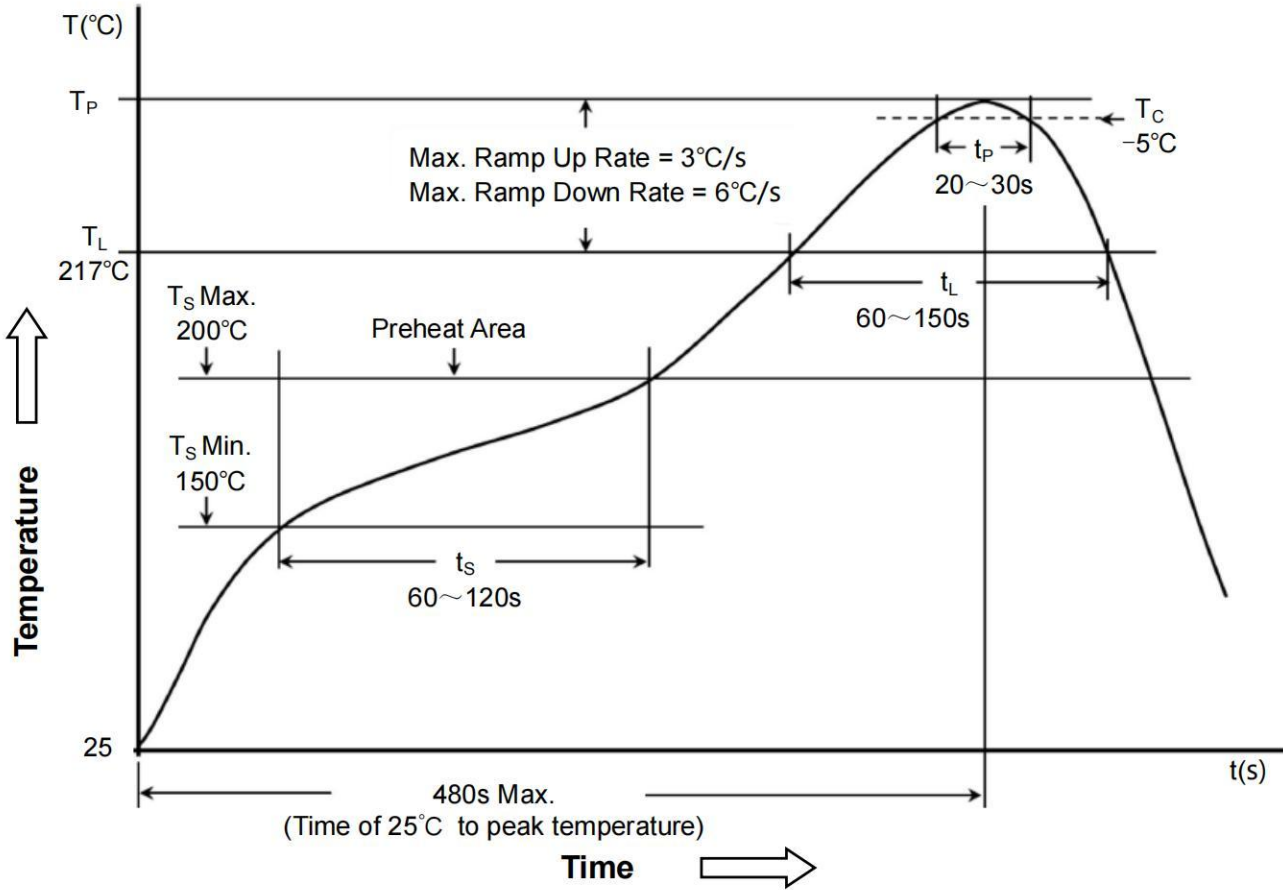


8 Soldering specification

焊接规格

8.1 Reflow profile for SMT components

SMT 回流焊温度曲线



8.2 Classification of peak package body temperature (Tp)

封装体峰值温度(Tp)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm ³	350 ~ 2000 mm ³	>2000 mm ³
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6 ~ 2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.

回流焊参照标准 IPC/JEDEC J-STD-020D.